(II) Applications of Major Substances by Shapes (No.2)

Shape / Substance	Single Crystal	Sintered or Amorphous	Powder	Porous or Through-Hole	Thin Film	Fiber	Composite or Bonded
Cadmium Sulphide CdS	∘Compound semiconductor	∘Fine powder sintered material (Cd^{2+} ion sensor)	∘Pigment ∘Fluorescencer	-	-	-	∘Solar cell (bonded with Cu_2S)
Silicon Nitride Si_3N_4	-	∘Thermal resistant fortifier ∘Thermal resistant vessel ∘Refractory	-	-	∘Ceramic coating ∘Insulation film for IC	-	-
Silicon Carbide SiC	-	∘Thermal resistant fortifier ∘Thermal resistant vessel ∘Refractory	∘Abrasive ∘Grinding material	-	-	∘Thermal resistant insulation material ∘Reinforcing material for cermet	∘Whetstone ∘Cermet
Carbon (diamond, graphite, amorphous) C	∘Jewelry (diamond)	∘Cutting tool (diamond) ∘Thermal resistant vessel (graphite) ∘Electric wave absorber	∘Abrasive (diamond) ∘Grinding material (diamond) ∘Lubricant (graphite)	∘Adsorbant (amorphous)	-	∘Carbon fiber (amorphous)	∘Cutting tool ∘Composite with metal on resin
Silicon Oxide SiO_2	∘Crystal oscillator	∘Mask substrate for IC ∘Quartz crucible	-	∘Adsorbant ∘Catalyst carrier ∘Secondary electron multiplier	-	∘Reinforcer for glass fiber ∘Optic communication fiber (super high strength)	∘Glass fiber ∘FRP
Ferrite (ion oxide)	∘Magnetic head	∘Magnetic head ∘Magnet core (soft) ∘Magnet (hard)	∘Powder for magnetic tape (needle powder) ∘Electric wave absorber	∘Catalyst	∘Magnetic tape	-	∘Magnetic tape
Boron Nitride BN	∘Cutter/grinder for precise processing	∘Cutting tool ∘Wire draw dice tool	∘Sheathed thermo-couple insulation ∘Crucible	-	∘Lubricant ∘Electric insulation ∘Varistor ∘EL device	∘Composite material	-